

B7 99P 1363

PATENTS ABSTRACTS OF JAPAN

E-927 May 14, 1990 Vol. 14/No. 225

(54) ELECTRONIC PARTS MOUNTING DEVICE

(11) 2-56944 (A) (43) 26.2.1990 (19) JP

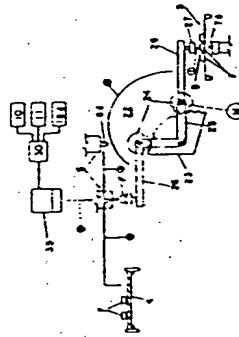
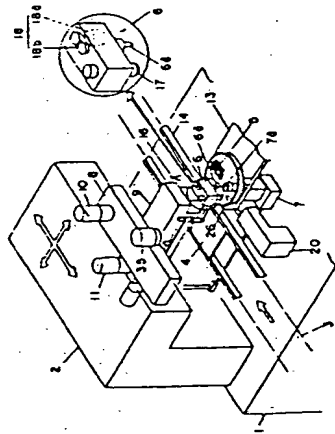
(21) Appl. No. 63-207646 (22) 22.8.1988

(71) MATSUSHITA ELECTRIC IND CO LTD (72) MANABU GOTO

(51) Int. Cl. H01L21/60, H05K13/04

PURPOSE: To precisely and automatically perform mounting on a board by controlling the nozzle of a transfer head so that it can be placed on the center of a flip chip on the basis of an observed result of a visual inspection.

CONSTITUTION: When XY directional moving devices 8, 9 are driven to move a camera 17 upward of a board 4, a position discrepancy of a printed pattern is observed and a suction part 27 of an arm 26 of an inside and outside reversing device 22 approaches a wafer 5, the suction part 27 is sucked on a bump forming face by a pin 7a to take up a flip chip F. Next, an xyθ-directional position discrepancy is observed on condition that the flip chip F is inverted. A transfer head 6 is moved on the basis of this observed result, the flip chip 27 is taken up and an XY-directional moving devices 8, 9 are driven so that a nozzle 6a can be placed on the center of the flip chip F. Thereby the inside and outside of the flip chip F is reversed to precisely mount on the board 4.



LEGENDE zu den Bibliographiedaten

(54) Titel der Patentanmeldung

(11) Nummer der JP-A2 Veröffentlichung

(21) Aktenzeichen der JP-Anmeldung

(43) Veröffentlichungstag

(22) Anmeldetag in Japan

(71) Anmelder

(72) Erfinder

(52) Japanische Patentklassifikation

(51) Internationale Patentklassifikation

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